



Features

- · Silicone free thermal gel
- · Shapeable and compressible
- · Low thermal impedance
- · No fluidity

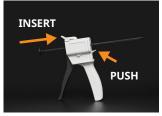
TG-NSP25 Non-silicone Thermal Putty

Application:

Best for high-speed or middle-power chipset

Electronic Components - 5G, Aerospace, AI, AIoT, AR/VR/MR/XR, Automotive, Consumer Devices, Datacom, Electric Vehicle, Electronic Products, Energy Storage, Industrial, Lighting Equipment, Medical, Military, Netcom, Panel, Power Electronics, Robot, Servers, Smart Home, Telecom, etc.

Operation Manual



① Push the latch and insert the stick.



2 Put the tube in and twist.



③ Close the cover.

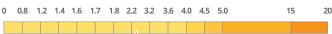


④ Take off the plug.

(The putty in the picture does not represent the actual product.)

Properties

Thermal Conductivity: 2.6 W/m•K



Properties	Unit	TG-NSP25	Tolerance	Test Method
Thermal Conductivity	W/m•K	2.6	±10%	ASTM D5470 Modified
Color	-	Gray	-	-
Viscosity	Pa∙s	5000	-	Brookfield
Density	g/cm ³	2.6	-	ASTM D792
Low MW Siloxane (D3-10)	ppm	0	-	GC/MS
Volume Resistivity	Ohm-m	10 ¹⁴	-	ASTM D257
Operating Temperature	°C	-50~+150	-	-
Standard Package	-	Tube/Pot	-	-

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